

IN THE ABSTRACT:

Please enter the attached substitute Abstract of the Disclosure for that originally filed with this application.

ABSTRACT OF THE DISCLOSURE

A heat sink-type cooling device for an integrated circuit having a base and plurality of fin extended upward. The plurality of fins are divided into more than one heat zones and said plurality of heat zones have a height drop between each two zones wherein a rectangular hole can also be punched on the plate end of said plurality of fin which is not connected with said base. By these heat zones with height drop between each two zones, the heat sink-type cooling device is able to match up the inner space allocation of the computer mainframe and be assembled even more easily into the computer mainframe so that heat is dispersed efficiently.